

Abstract

A semiconductor device that enables a test for individual IC chips mounted on an interposer is provided. In the semiconductor device having the interposer on which a first
5 IC chip and a second IC chip are mounted, the first IC chip and the second IC chip are connected to outside the interposer by input wiring and output wiring, respectively, and a transistor element serving as a switch is inserted in series
10 into the wiring connecting between the first IC chip and the second IC chip.